

Title (en)
THERMOPLASTIC RESIN COMPOSITION AND MOLDING THEREOF

Title (de)
THERMOPLASTISCHE HARZZUSAMMENSETZUNG UND DEREN FORMUNG

Title (fr)
COMPOSITION DE RESINE THERMOPLASTIQUE ET SON MOULAGE

Publication
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Application
EP 06731911 A 20060414

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Abstract (en)
[origin: EP1876206A1] The objective of the present invention is to provide a thermoplastic resin composition excelling in translucency, impact resistance, heat resistance and fluidity, particularly a thermoplastic resin composition that in the production of thermoplastic resin molded items through extrusion processing, molding processing, etc., permits a wide tolerance range of processing conditions, such as low susceptibility to quality deterioration by thermal history, excelling in translucency, impact resistance, heat resistance and fluidity; and a molding thereof. The present composition comprises a rubber-reinforced resin consisting of a rubber-reinforced copolymeric resin obtained by polymerization of a vinyl-based monomer including an aromatic vinyl compound in the presence of a rubbery polymer having refractive index in the range from 1.520-1.580, or a mixture of this rubber-reinforced copolymeric resin and a (co)polymer of the above vinyl-based monomer, and a polycarbonate resin in specified ratio, and further comprises a phosphoric compound.

IPC 8 full level
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Citation (search report)

- [XY] WO 0232999 A2 20020425 - GEN ELECTRIC [US]
- [Y] WO 03106562 A1 20031224 - GEN ELECTRIC [US]
- See references of WO 2006118007A1

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